

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.4	100.0	0.67
Subtotal				0.4	100	0.67
Wire	Impurity	Non hazardous		0	0.01	0
	Pure metal	Copper (Cu)	7440-50-8	0.31	99.99	0.53
Subtotal				0.31	100	0.53
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.03	0.02
	Copper alloy	Zinc (Zn)	7440-66-6	0.06	0.15	0.1
	Copper alloy	Iron (Fe)	7439-89-6	0.88	2.29	1.49
	Copper alloy	Copper (Cu)	7440-50-8	37.31	96.97	63.19
	Copper alloy	Silver (Ag)	7440-22-4	0.22	0.56	0.36
Subtotal				38.48	100	65.16
Mould Compound	Polymer	Epoxy Phenol Novolac resin (generic)	28064-14-4	2.06	3.5	3.49
	Filler	Silica -amorphous-	7631-86-9	4.71	8.0	7.98
	Filler	Silica fused	60676-86-0	47.1	80.0	79.76
	Carbon Black	Carbon black	1333-86-4	0.29	0.5	0.5
	Polymer	Epoxy resin system		4.71	8.0	7.98
Subtotal				58.87	100	99.71
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.83	100.0	3.1
Subtotal				1.83	100	3.1
Die Attach	Hardener	Hardener		0.01	5.0	0.01
	Phenolic resin	Phenolic resin		0.01	5.0	0.01
	Epoxy resin	Epoxy resin system		0.01	5.0	0.01
	Lead alloy	Silver (Ag)	7440-22-4	0.09	85.0	0.16
Subtotal				0.12	100	0.19
Total				100.01	100	169.36

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